

Optical PCBs

Bridging the gap between fibers & PIC

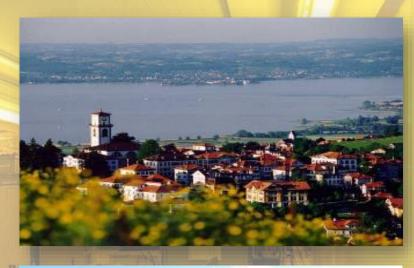
EPIC Tech Watch @ ECOC2023 Glasgow

Date: 04.10.2023

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Who we are

- SME based in Heiden, Switzerland
- Spin-off from Varioprint AG (PCB)
- Designer & Manufacturer of photonic boards
- Applications & Markets:
 - Photonic Sensing (Medical, Industrial, Environmental)
 - High-speed on-board communication (Telecom, Aerospace)
 - Photonic chip packaging (Telecom, Sensing,...)







What we do: Photonic Boards / Optical PCBs

vario-optics manufactures optical printed circuit boards (oPCBs)

Design & Development

- Feasibility Studies, Engineering
- Electro-optical Co-Design

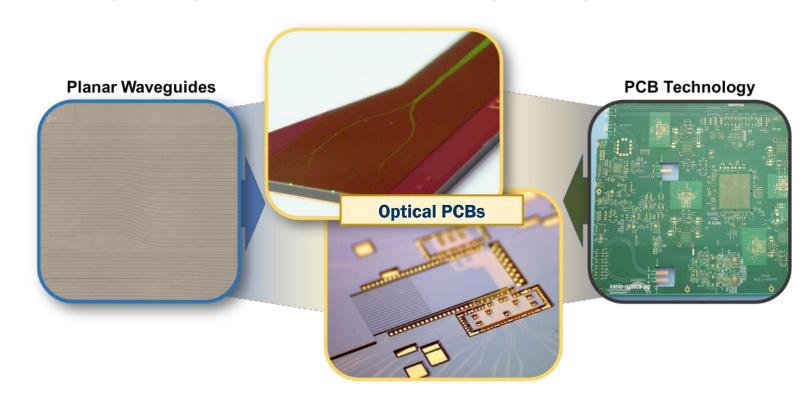
Focus

Manufacturing

- Prototyping / Evalution Boards
- Custom Runs
- Pilot Production / Volume

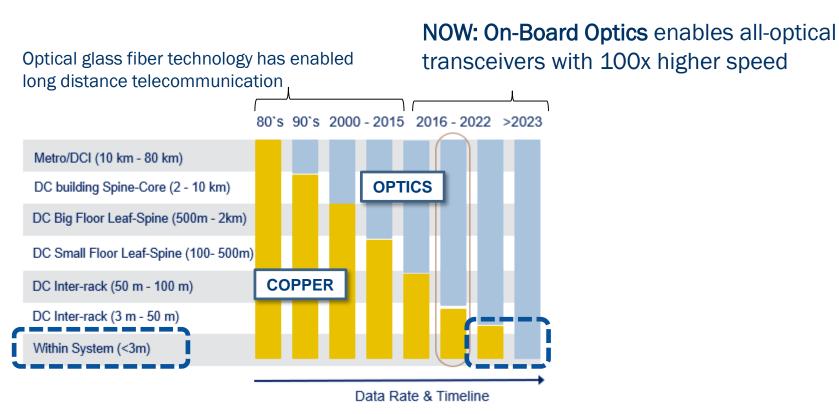
Assembly & Integration

- Providing Interfaces
- Support for packaging & assembly





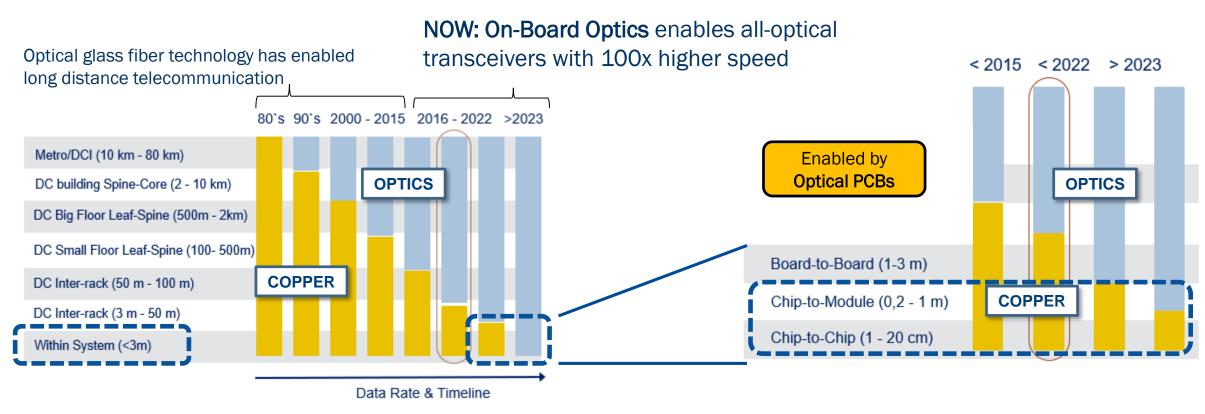
The Poblem: Electrical Interconnects Reach Their Bandwidth Limit - NOW!



Source: Yole 2022 market report on Optical Transceiver for Datacom & Telecom Market, Graphic adapted



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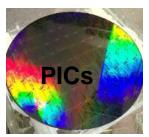


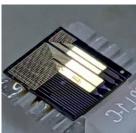
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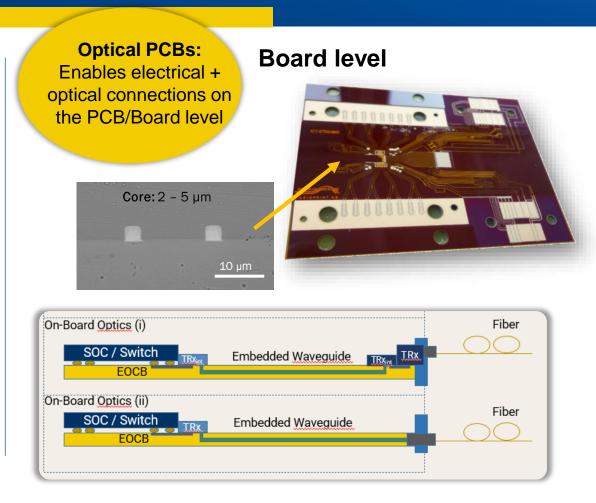


The PIC packaging bottleneck

Chip level (PICs)







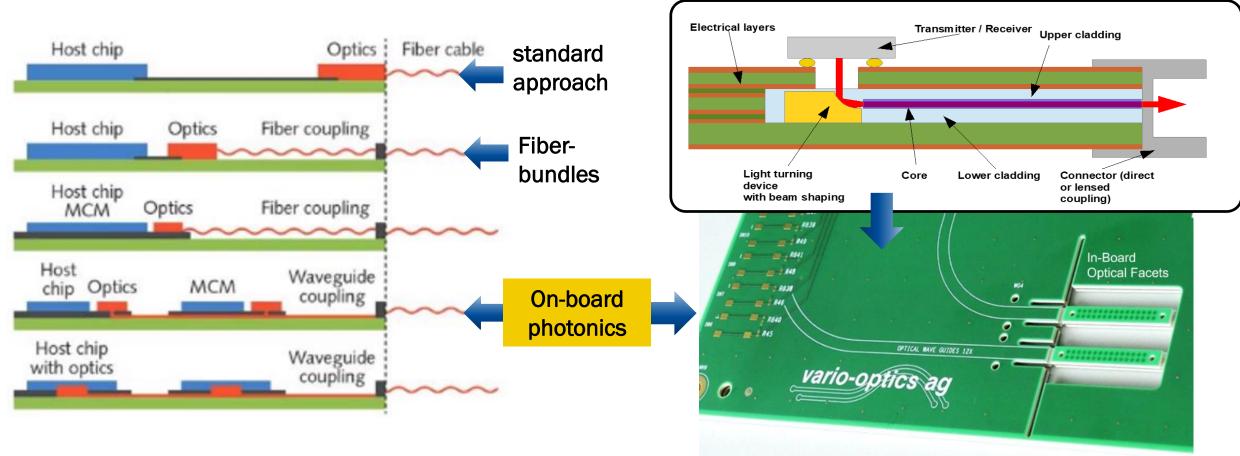




1) On-Board Photonics

100G demonstratorboard within COBO to be shown at OFC24





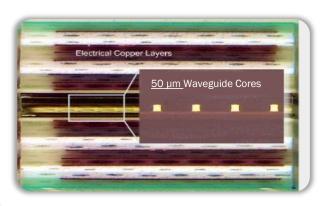


1) On-Board Photonics

Planar waveguides are integrated into conventional electrical printed circuit boards

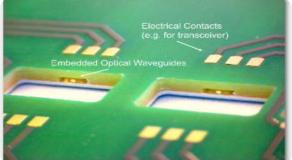
- No optical fibers
- Replacing electrical connections for high-speed signals

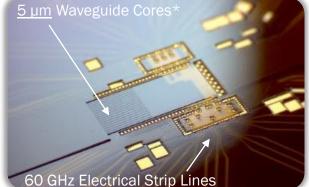
Planar optical waveguides & structures, optimized for a broad wavelength spectrum



Combination with PCBs: integration of optical and electrical connections







High integration density for any number of optical channels

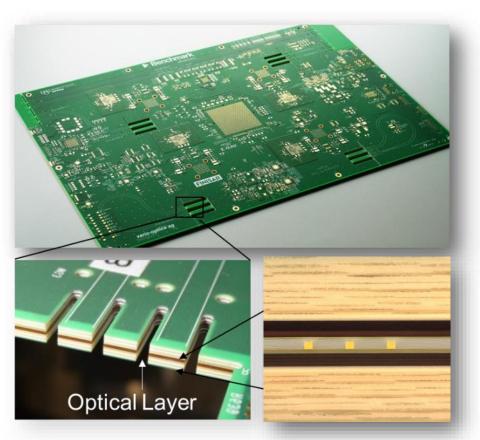


Access to photonic functionalities via standardized electrooptic interfaces

* 16x smaller than a hair (80 – 100 μ m)



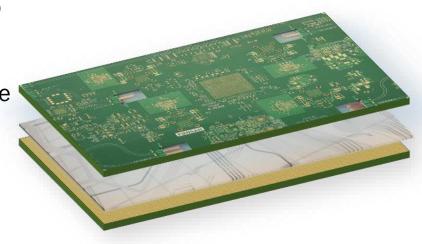
1) On-Board Photonics: Reliability



 Max Panel Size (MM): up to 305 – 460 mm²

• Reflow soldering compatible (260 °C, 0.5 min)

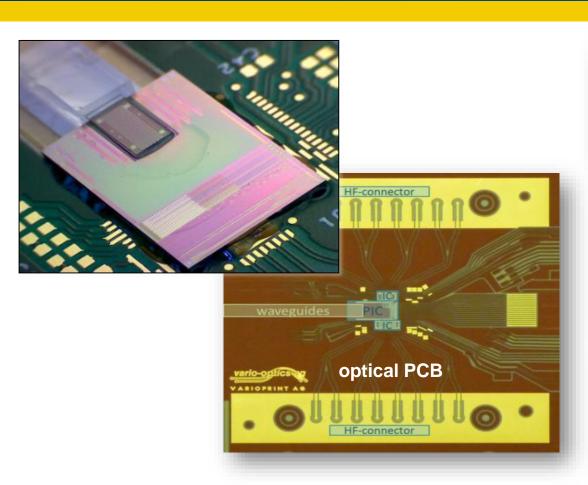
 Recently successfully passed ESA technology validation



| Environmental Stability: | |
|--------------------------|--|
| Operating Temperature | 120°C |
| Environmental Test | 85% rel.h / 85°C for 2000h (Telcordia) |
| Temperature Cycling | - 50°C to + 100°C |

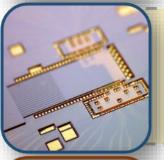


2) chip-to-chip optical interconnects PIC Packaging Platform



Planar Waveguides

High I/O number optical Fan-outs
On-chip mode conversion (e.g. SiPh to Fiber)
Polarization maintaining Waveguides



Optical Interfaces

Efficient PIC-Waveguide Coupling (Adiabatic or Butt-Coupling)
Fiber-Interface & Connectors



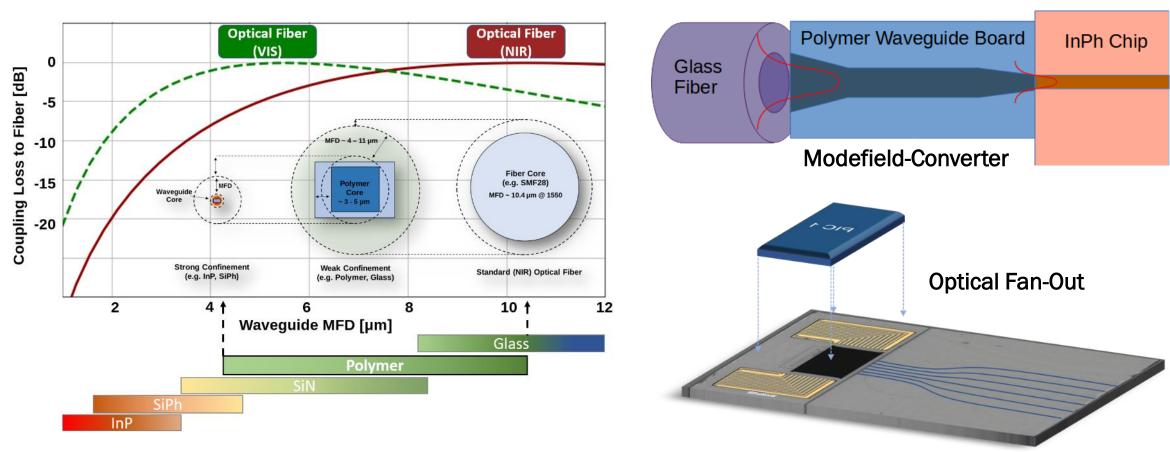
Electrical Interface

Metallization & PCB Integration Fine-Pitch, Flip-Chip Bonding RF Interface



2) Polymer Photonics for advanced PIC Packaging

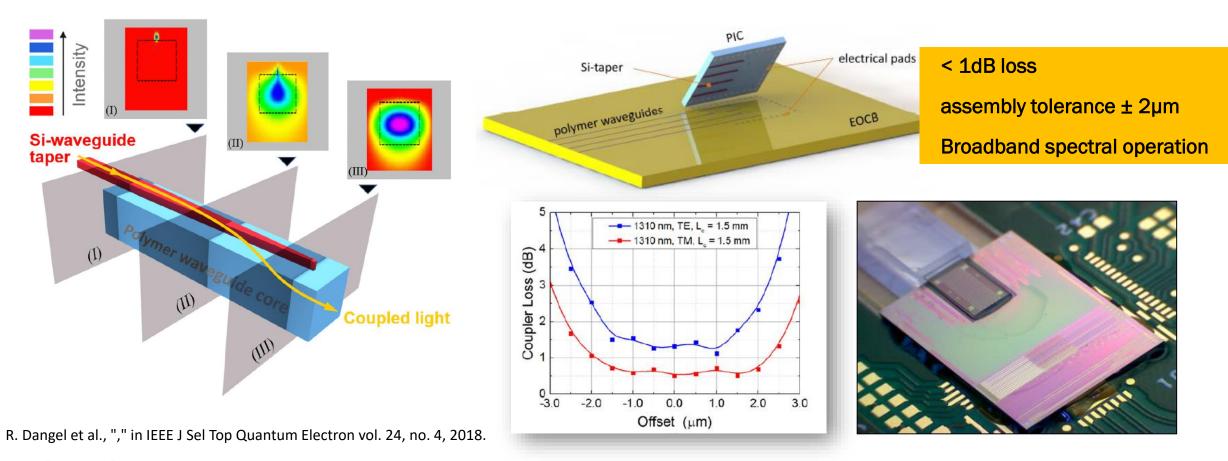
Edge-Coupling





2) Polymer Photonics for advanced PIC Packaging

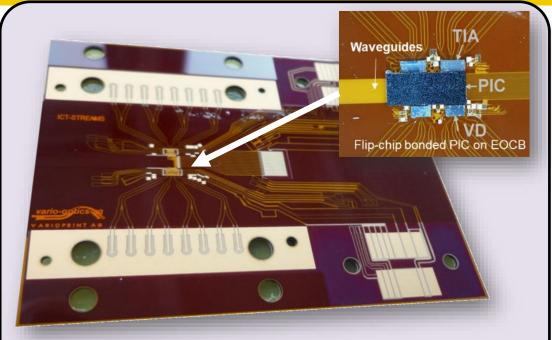
Adiabatic (Evanescent)-Coupling



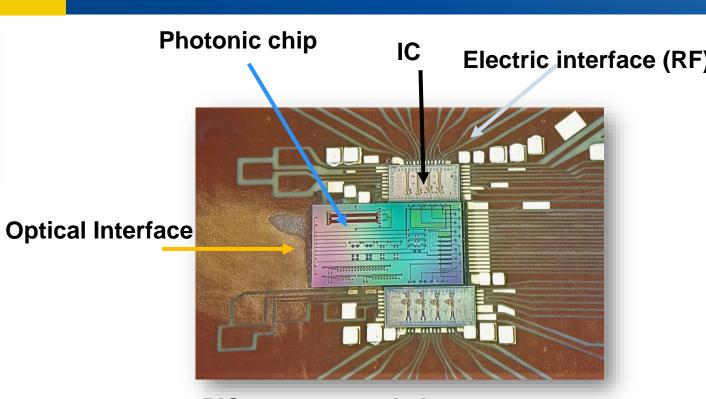


PICs are not stand-alone systems

electro-optical-mechanical-thermal aspects



- 70 GHz photonic board for a transceiver
- 400 Gb/s (8-channel) data-transmission
- 5pJ/bit (50Gbit/s)



- PIC are not stand-alone systems
 - o (Fiber, Waveguides, ICs, RF, Thermal...)



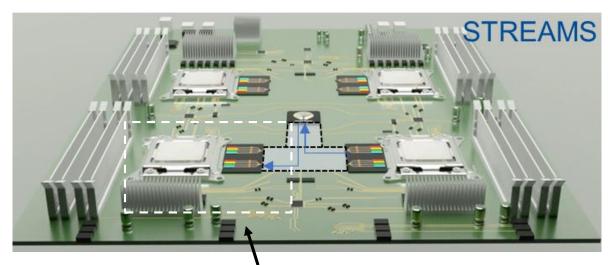
Chip-packaging example: ICT STREAMS

Substrate for High-Speed optical Chip-Chip Communication, Silicon Photonics

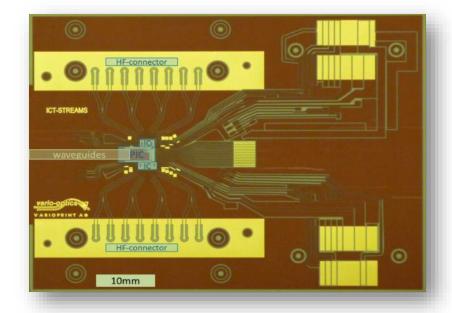


EC-funded project ICT STREAMS:

Efficient optical any-to-any communication for multi-socket boards (beyond 4 nodes, 25Tbit/s)







Photonic motherboard to host ICs, PICs

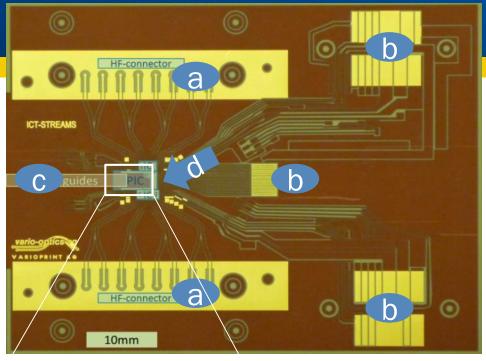
+ el. & optical on-board communication

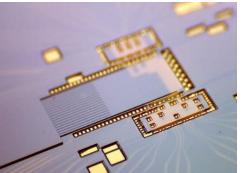


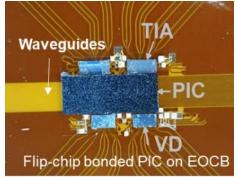
Chip-packaging example: ICT STREAMS

Substrate for High-Speed optical Chip-Chip Communication, Silicon Photonics









High-performance **Electro-optical circuit board** for high-data rate Silicon Photonic transceivers, with ultra-low power consumption

- a) & b) high-frequency RF electrical signal interface
- c) Polymer Singlemode waveguides (@1310 nm)
- d) adiabatic optical-coupling interface (< 1dB loss; assembly tolerance ± 2µm; Broadband spectral operation)
 - 400 Gb/s (8-channel) data-transmission
 - 70% power reduction (compared to electrical communication)
 - **5pJ/bit (50Gbit/s)** vs. **16pJ/bit (QPI)***





^{*} T. Lamprecht et al., "EOCB-Platform for Integrated Photonic Chips Direct-on-Board Assembly within Tb/s Applications" , IEEE 68th Electronic Components and Technology Conference (ECTC), San Diego, USA, 2018, pp. 854-858

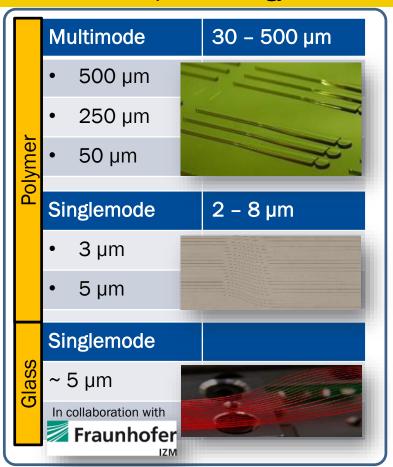
Summary: vario-optics Polymer Photonics Portfolio

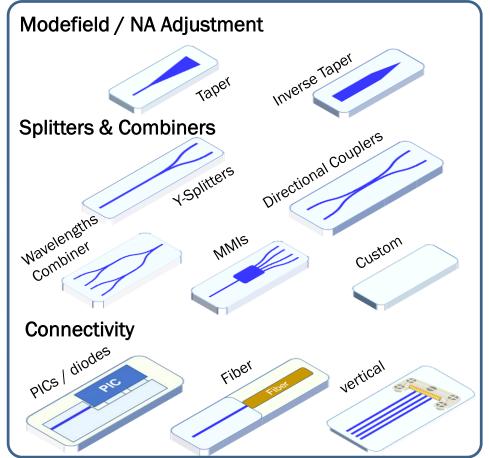
> 15 years of Waveguide R&D Know-How

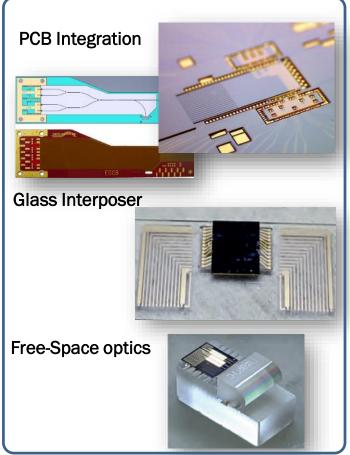
Process / Technology

Functionality

Integration & Assembly











Let's keep up inspiring

Globally leading, energy saving high-speed solution provider for optical communication and miniaturized sensors

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